Small switching (–20V, –1.5A)

QS5U23

Features

- The QS5U23 conbines Pch MOSFET with a Schottky barrier diode in a single TSMT5 package.
- 2) Pch MOSSFET have a low on-state resistance with a fast switching.
- 3) Pch MOSFET is reacted a low voltage drive(2.5V)
- 4) The independently connected Schottky barrier diode have a low forward voltage.

Applications

Load switch, DC/DC conversion

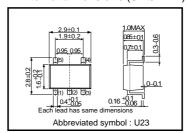
Structure

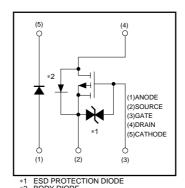
- Silicon P-channel MOSFET
- Schottky Barrier DIODE

Packaging specifications

Туре	Package	Taping
	Code	TR
	Basic ordering unit (pieces)	3000
QS5U23		0

●External dimensions (Units : mm)





Equivalent circuit

● Absolute maximum ratings (Ta=25°C)

< MOSFET > Parameter		Symbol	Limits		Unit	
Drain-source voltage		Voss	-20	V		
Gate-source voltage		Vgss	±12	V		
Drain current	Continuous	lo	±1.5	А		
	Pulsed	IDP	±6.0	А	Pw≦10μs, Duty cycle≦1%	
Source current (Body diode)	Continuous	Is	-0.75	А		
	Pulsed	Isp	-3.0	А	Pw≦10μs, Duty cycle≦1%	
Channel temperature		Tch	150	°C		
 ≤ Di > Repetitive peak reverse voltage Reverse voltage 				T 1/		
	erse voltage	V _{RM}	30 20	V		
Reverse voltage	erse voltage			1 -		
	-	VR	20	V	60Hz / 1CYC	
Reverse voltage Forward current	ge peak	V _R	20 0.5	V	60Hz / 1CYC	
Reverse voltage Forward current Forward current sure	ge peak e	VR IF	20 0.5 2.0	V A A	60Hz / 1CYC	
Reverse voltage Forward current Forward current sure	ge peak e	VR IF	20 0.5 2.0	V A A °C	60Hz / 1CYC AL MOUNTED ON MIC BOARD	

● Electrical characteristics (Ta=25°C)

< MOSFET >

< MOSFET >							
Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions	
Gate-source leakage	Igss	_	_	±10	μΑ	Vgs=±12V/ Vps=0V	
Drain-source breakdown voltage	V(BR)DSS	-20	_	_	V	In=-1mA/ Vgs=0V	
Zero gate voltage drain current	IDSS	-	_	-1	μΑ	V _{DS} =-20V/ V _{GS} =0V	
Gate threshold voltage	VGS(th)	-0.7	_	-2.0	V	VDS=-10V/ ID=-1mA	
		1	160	200	mΩ	In=-1.5A, Vgs=-4.5V	
Static drain-source	RDS(on) *Pulsed	-	180	240	mΩ	In=-1.5A, Vgs=-4V	
on-state resistance	*Fulseu	_	260	340	mΩ	ID=-0.75A, Vgs=-2.5V	
Forward transfer admittance	Y _{fs} *Pulsed	1.0	_	_	S	V _{DS} =-10V, I _D =-0.75A	
Input capacitance	Ciss	-	325	_	pF	VDS=-10V	
Output capacitance	Coss	-	60	_	pF	Vgs=0V f=1MHz	
Reverse transfer capacitance	Crss	ı	40	_	pF		
Turn-on delay time	t _{d(on)} *Pulsed	_	10	_	ns	ID=-0.75A	
Rise Time	t _r *Pulsed	-	10	_	ns	V _{DD} ≒ −15	
Turn off delay time	t _{d(off)} *Pulsed	-	35	_	ns	Vgs=-4.5V RL=20Ω	
Fall time	*Pulsed	ı	10	_	ns	R _G s=10Ω	
Total gate charge	Qg	ı	4.2	_	nC	Vpp ≒ −15V	
Gate-source charge	Qgs	-	1.0	_	nC	Vgs=-4.5V	
Gate-drain charge	Qgd	ı	1.1	_	nC	ID=-1.5A	
< MOSFET >Body diode(source-d	rain)						
Forward voltage	VSD	-	-	-1.2	V	Is=-0.75A/ Vgs=0V	
< Di >							
	VF	_		0.36	V	IF=0.1A	
Foward voltage drop		_	-	0.47	V	I==0.5A	
Reverse leakage	lR	_	_	100	μΑ	V _R =20V	

Electrical characteristic curves Resistance Drain Current: -lb (A) : Drain–Source On–State Ros(on)[mΩ] Static Drain-Source On-State | Ros(on)[mΩ] 0.1 0.01 Static 0.001 Drain Current : -Ip[A] Gate-Source Voltage: Vgs[V] Fig.2 Static Drain-Source On-State Fig.3 Static Drain-Source On-State Resistance vs. Drain Current Resistancevs. Drain Current Fig.1 Typical Transfer Characteristics 400 Static Drain-Source On-State Resistance Static Drain-Source On-State Resistance Static Drain-Source On–State Resistance $\underset{\Xi}{\text{Ros}(\text{on})[m\Omega]}$ 350 300 Ros(on)[mΩ] 100 Drain Current : -lo[A] Fig.6 Static Drain-Source On-State $Gate-Source\ Voltage:-Vcs[V]$ Fig.4 Static Drain-Source On-State Fig.5 Static Drain-Source On-State Resistance vs. Drain Current Resistance vs. Drain-Current Resistance vs.Gate-Source Voltage 10000 Ta=25℃ f=1MHz VGS=0V VGS=-4.5V RG=10Ω Reverse Drain Current : -lbr[A] Switching Time : t [ns] Capacitance : C [pF] 1000 100 Crss 0.01

Drain Current : -ID[A]

Fig.9 Switching Characteristics

$$\label{eq:decomposition} \begin{split} & \mathsf{Drain}\text{-}\mathsf{Source}\ \mathsf{Voltage}: -\mathsf{Vps}[\mathsf{V}] \\ & \mathsf{Fig.8}\ \mathsf{Typical}\ \mathsf{Capactitance} \end{split}$$

vs. Drain-Source Voltage

Source-Drain Voltage: -Vsp[V]

Fig.7 Reverse Drain Current VS. Source-Drain Current

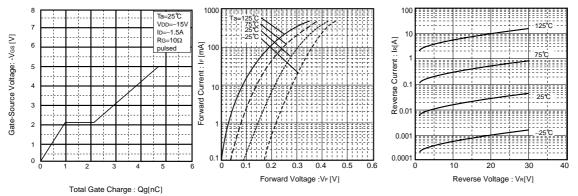


Fig.10 Dynamic Input Characteristics Fig.11 Forward Temperature Characteristics Fig.12 Reverse Temperature Characteristics

Measurement circuits

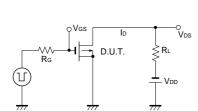


Fig.13 Switching Time Measurement Circuit

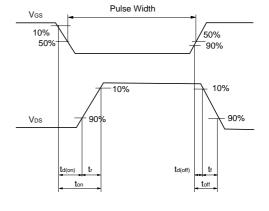


Fig.14 Switching Waveforms

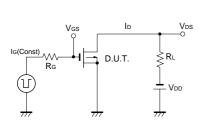


Fig.15 Gate Charge Measurement Circuit

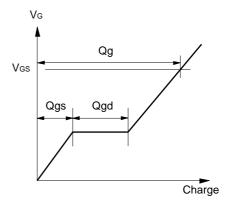


Fig.16 Gate Charge Waveforms

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